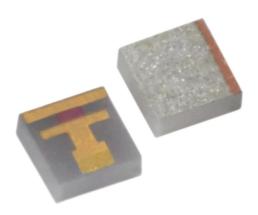
## High Reliability Wire Bondable Chip Terminations



Smiths Interconnect's HR-CTX Series is designed to offer excellent broadband performance up to 64 GHz, with optimized return loss for multiple frequency bands.

The HR-CTX high frequency termination series offers excellent broadband performance up to 64GHz and unrivalled power rating capability up to 5 Watts in a small 0404 package. Its small footprint allows customers to save space and weight on the board, while the total thin film design optimized on Aluminum Nitride offers a high power dissipation.

This lightweight and very compact termination ensures optimized return loss for multiple frequency bands and a wide array of applications. This allows the customer to use a single chip in multiple applications, reducing the total cost of ownership.

The HR-CTX high frequency termination series is qualified for space applications, eliminating the need for customer's inhouse qualification. It is supplied with all the necessary test and qualification data to ensure flight compliance.

The HR-CTX series
DC-64 GHz chip
termination pushes
the limits of frequency
and power in a small,
easy-to-implement,
high-reliability product
qualified for space
applications.

#### Features and Benefits

- Power rating up to 5 Watts, increased by up to 5x over alternative solutions
- Frequency rating DC to 64 GHz with optimal broad band performance
- Excellent VSWR (1.25:1 Typical)
- Total thin film construction
- Reduced footprint allowing for space and weight savings on the board: 0.040" x 0.040" x 0.015"
- Space qualified based on MIL-PRF-55342

## **Applications**

- Amplifier Circuits
- Isolators
- Transmit/Receive Modules
- Up/Down Converters
- Instrumentation
- Satellite Communications
- Radar
- Broadcast

## **Technical Characteristics**

Mounting Configuration Options	HR-CT0404ALN1WB1	HR-CT0404ALN2WB1		
Electrical				
Nominal Impedance	50 ohms ± 10%			
Frequency Range	DC-42.5 GHz	DC-64 GHz		
Input Power CW	5 Watts	1 Watt		
Peak Power	10X CW power based on 1 µS pulse width @ 1% Duty	Cycle		
VSWR	1.25:1 Typical			
	Note: When properly matched in a 50 Ohm system using Smiths Interconnect's Suggested Mounting Guidelines.			
Environmental				
Operating Temperature	-55°C to +150°C			
Storage Temperature	-65°C to +150°C			
Temperature Coefficient	± 200 PPM/°C Max			
Moisture Sensitivity Level	MSL 1 - Unlimited			
Mechanical				
Substrate Material	Aluminum Nitride			
Resistive Film	Thin Film, Tantalum Nitride			
Terminal Material	Thin Film, Gold over Nickel			
Ground Plane	Thin Film, Solderable Silver over Platinum			
Protective Coating	Silicon Nitride			
Marking				
Unit Marking	N	one		
Quality Assurance				
	Sample visual and mechanical inspection - 1.0 AQL per mechanical drawing requirements.			
	Periodic electrical inspection performed for commercial grade products.			
	High reliability tested products are available per MIL-PR	F-55342.		
Packaging				
Standard Packaging	Tape and Reel or Waffle Pack			

## **HR-CTX Series**

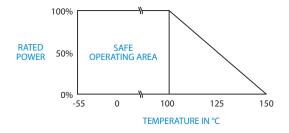
## Test Parameters per Test Plan TP-9311

Test	Sample Qty	Test Standard and Method	Test Condition	
	100% &			
Group A Inspection	7 destruct			
Visual / Mechanical	100% &	MIL-PRF-55342	30X to 60X Magnification	
Initial Electrical (DC/RF) Inspection	7 destruct 100%	MIL-PRF-55342	DC Resistance / 7 samples RF - Limits per datashee	
Thermal Shock	100%	MIL-PRF-55342, MIL-STD-202, Method 107	10 Cycles -55 to +125°C	
Burn In/Bake	100%	MIL-PRF-55342, MIL-STD-202, Method 108	Stabilization Bake @ 150°C for *Exception 100 Hours	
Final Electrical (RF) Inspection	100% & 7 destruct	MIL-PRF-55342	DC Resistance / 7 samples RF - Limits per datasheet	
Percent Defective Allowable (PDA)	100%	Per Smiths Interconnect TP-9311	10% allowable	
Group B Inspection	4			
Subgroup 1	2			
Electrical (RF) Inspection	2	MIL-PRF-55342	RF - Limits per datasheet	
Liectrical (Ki / Hispection	2	THE TIM 33342	Ni Elinis per obtosneet	
Low Temperature Operation	2	MIL-PRF-55342	Maximum Rated Input Power @-55°C * Exception -55°C	
Electrical (RF) Inspection	2	MIL-PRF-55342	RF - Limits per datasheet	
High Temperature Exposure	2	MIL-PRF-55342	100 hours @ *Exception 150°C	
Short Term Overload	2	MIL-PRF-55343 Method 4.8.6	2.5 times maximum voltage for 5 seconds	
Electrical (RF) Inspection	2	MIL-PRF-55342	RF - Limits per datasheet	
Subgroup 2	2			
Termination Adhesion	2	MIL-PRF-55342, MIL-STD-202, Method 211	Test Condition A - Pull Test - *Exception 15 Grams	
Bondability	2	MIL-PRF-55342	Mounted to metallized substrate, a minimum of 2 bonds per chip using .001" diameter gold wire - Pull rate 50 ± 10 secondsper inch max	
Termination Solderability (Resistance to Soldering Heat)	2	MIL-PRF-55342, MIL-STD-202, Method 210	Test Condition B - Solder Dip - Sn/Pb 220°C for 5 seconds	
Group C Inspection	3			
Initial Electrical (RF) Inspection	3	MIL-PRF-55342	RF - Limits per datasheet	
Load Life Test	3	MIL-PRF-55342, MIL-STD-202, Method 108	Test Condition D - Maximum Rated Input Power @ 100°C for 1000 Hours, Electrical measurements	
Final Electrical (RF) Inspection	3	MIL-PRF-55342	made @ 0, 250, 500, 1000 hours RF - Limits per datasheet	

## Sample Quantities and Lead Times Product Series Test Sample Requirements and Lead Times for TP-9311

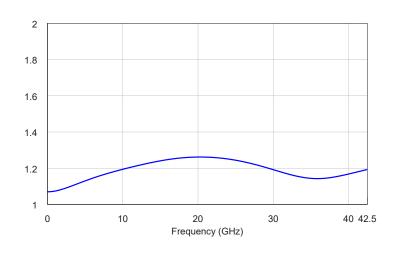
Test Level	HR-CTX SERIES	Lead Time
Group A Total	7 Samples	14 Weeks ARO
Group A RF	Add 7 samples	
Group A & B Total	7 Samples Total	22 Weeks ARO
Group B Sub-group 1	2 samples from Group A	
Group B Sub-group 2	2 samples from Group A	
Group A, B & C Total	7 Samples Total	24 Weeks ARO
Group C Life	3 Samples from Group A for life test	

## Power Derating Curve

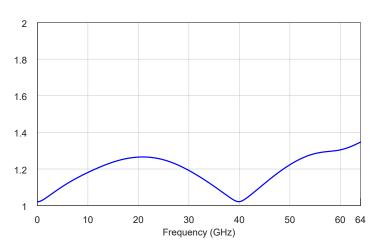


## Typical Data

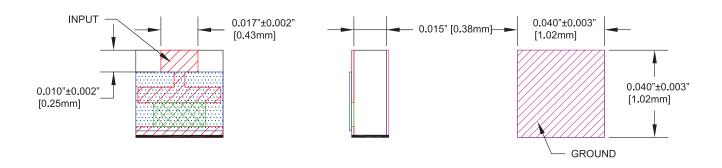
#### HR-CT0404ALN1WB1 Series VSWR



#### HR-CT04042WB1 Series VSWR



## Mechanical Specification



Unless otherwise specified, tolerance:  $X.XXX = \pm 0.01'' X.XXX = \pm 0.001''$ 

## How To Order

Specify Model Number: HR-CT0404ALNXWB1

H R		СТ	0 4 0 4	ALN		W B 1
1	2	3	4	5	6	7
1 Component Typ	е	H R High Reliability				
2 Test Code		A Group A testing B Group A and B testing C Group A, B and C testing				
3 Device Type		C T Chip Termination				
4 Device Size		0 4 0 4 0.040 Length x 0.040 Width				
5 Substrate Mater	rial	A L N Aluminum Nitride				
6 Frequency Code	9	1 DC to 42.5 GHz 2 DC to 64.0 GHz				
7 Terminal Finish		W B 1 Wire bondable				

# Worldwide Support

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